

STARPOWER

SEMICONDUCTOR

IGBT

GD150MLT60L3SF

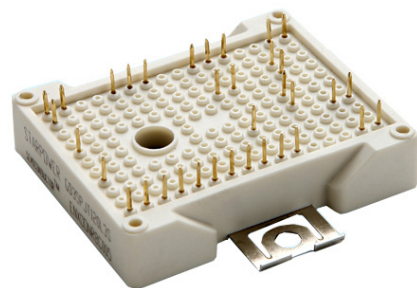
600V/150A 3-level and PressFIT

General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as 3-level-application.

Features

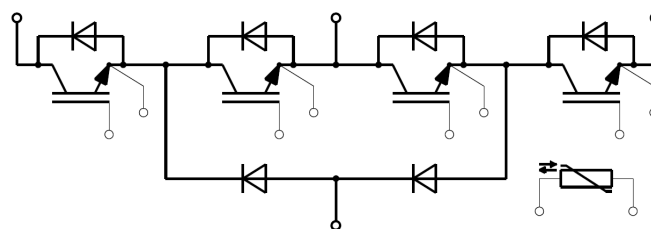
- Low $V_{CE(sat)}$ Trench IGBT technology
- Low switching loss
- 6 μ s short circuit capability
- $V_{CE(sat)}$ with positive temperature coefficient
- Maximum junction temperature 175°C
- Fast & soft reverse recovery anti-parallel FWD
- PressFIT contact technology
- Low inductance case



Typical Applications

- Solar power
- UPS
- 3-level-application

Equivalent Circuit Schematic



Absolute Maximum Ratings $T_C=25^{\circ}\text{C}$ unless otherwise noted**T1-T4 IGBT**

Symbol	Description	Value	Unit
V_{CES}	Collector-Emitter Voltage	600	V
V_{GES}	Gate-Emitter Voltage	± 20	V
I_C	Collector Current @ $T_C=25^{\circ}\text{C}$ @ $T_C=80^{\circ}\text{C}$	205 150	A
I_{CM}	Pulsed Collector Current $t_p=1\text{ms}$	300	A
P_D	Maximum Power Dissipation @ $T_j=175^{\circ}\text{C}$	549	W

D1-D4 Diode

Symbol	Description	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	600	V
I_F	Diode Continuous Forward Current	150	A
I_{FM}	Diode Maximum Forward Current $t_p=1\text{ms}$	300	A

D5,D6 Diode

Symbol	Description	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	600	V
I_F	Diode Continuous Forward Current	150	A
I_{FM}	Diode Maximum Forward Current $t_p=1\text{ms}$	300	A

Module

Symbol	Description	Value	Unit
T_{jmax}	Maximum Junction Temperature	175	$^{\circ}\text{C}$
T_{jop}	Operating Junction Temperature	-40 to +150	$^{\circ}\text{C}$
T_{STG}	Storage Temperature Range	-40 to +125	$^{\circ}\text{C}$
V_{ISO}	Isolation Voltage RMS, $f=50\text{Hz}$, $t=1\text{min}$	2500	V

T1-T4 IGBT Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=150\text{A}, V_{GE}=15\text{V}, T_j=25^{\circ}\text{C}$		1.45	1.90	V
		$I_C=150\text{A}, V_{GE}=15\text{V}, T_j=125^{\circ}\text{C}$		1.60		
		$I_C=150\text{A}, V_{GE}=15\text{V}, T_j=150^{\circ}\text{C}$		1.70		
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=2.4\text{mA}, V_{CE}=V_{GE}, T_j=25^{\circ}\text{C}$	5.1	5.8	6.4	V
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0\text{V}, T_j=25^{\circ}\text{C}$			1.0	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0\text{V}, T_j=25^{\circ}\text{C}$			400	nA
R_{Gint}	Internal Gate Resistance			2.0		Ω
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}, f=1\text{MHz}, V_{GE}=0\text{V}$		9.24		nF
C_{res}	Reverse Transfer Capacitance			0.27		nF
Q_G	Gate Charge	$V_{GE}=-15 \dots +15\text{V}$		1.60		μC
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=300\text{V}, I_C=150\text{A}, R_G=3.3\Omega, V_{GE}=\pm 15\text{V}, T_j=25^{\circ}\text{C}$		86		ns
t_r	Rise Time			40		ns
$t_{d(off)}$	Turn-Off Delay Time			302		ns
t_f	Fall Time			88		ns
E_{on}	Turn-On Switching Loss			1.22		mJ
E_{off}	Turn-Off Switching Loss			4.13		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=300\text{V}, I_C=150\text{A}, R_G=3.3\Omega, V_{GE}=\pm 15\text{V}, T_j=125^{\circ}\text{C}$		100		ns
t_r	Rise Time			45		ns
$t_{d(off)}$	Turn-Off Delay Time			332		ns
t_f	Fall Time			130		ns
E_{on}	Turn-On Switching Loss			1.73		mJ
E_{off}	Turn-Off Switching Loss			5.08		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=300\text{V}, I_C=150\text{A}, R_G=3.3\Omega, V_{GE}=\pm 15\text{V}, T_j=150^{\circ}\text{C}$		108		ns
t_r	Rise Time			46		ns
$t_{d(off)}$	Turn-Off Delay Time			340		ns
t_f	Fall Time			138		ns
E_{on}	Turn-On Switching Loss			1.95		mJ
E_{off}	Turn-Off Switching Loss			5.40		mJ
I_{SC}	SC Data	$t_p \leq 6\mu\text{s}, V_{GE}=15\text{V}, T_j=150^{\circ}\text{C}, V_{CC}=360\text{V}, V_{CEM} \leq 600\text{V}$		750		A

D1-D4 Diode Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Diode Forward Voltage	$I_F=150\text{A}, V_{GE}=0\text{V}, T_j=25^{\circ}\text{C}$		1.55	1.95	V
		$I_F=150\text{A}, V_{GE}=0\text{V}, T_j=125^{\circ}\text{C}$		1.50		
		$I_F=150\text{A}, V_{GE}=0\text{V}, T_j=150^{\circ}\text{C}$		1.45		
Q_r	Recovered Charge	$V_R=300\text{V}, I_F=150\text{A},$ $-di/dt=2400\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=25^{\circ}\text{C}$		6.8		μC
I_{RM}	Peak Reverse Recovery Current			82		A
E_{rec}	Reverse Recovery Energy			1.38		mJ
Q_r	Recovered Charge	$V_R=300\text{V}, I_F=150\text{A},$ $-di/dt=2400\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=125^{\circ}\text{C}$		11.4		μC
I_{RM}	Peak Reverse Recovery Current			106		A
E_{rec}	Reverse Recovery Energy			2.52		mJ
Q_r	Recovered Charge	$V_R=300\text{V}, I_F=150\text{A},$ $-di/dt=2400\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=150^{\circ}\text{C}$		13.3		μC
I_{RM}	Peak Reverse Recovery Current			112		A
E_{rec}	Reverse Recovery Energy			3.00		mJ

D5,D6 Diode Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Diode Forward Voltage	$I_F=150\text{A}, V_{GE}=0\text{V}, T_j=25^{\circ}\text{C}$		1.55	1.95	V
		$I_F=150\text{A}, V_{GE}=0\text{V}, T_j=125^{\circ}\text{C}$		1.50		
		$I_F=150\text{A}, V_{GE}=0\text{V}, T_j=150^{\circ}\text{C}$		1.45		
Q_r	Recovered Charge	$V_R=300\text{V}, I_F=150\text{A},$ $-di/dt=2400\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=25^{\circ}\text{C}$		6.8		μC
I_{RM}	Peak Reverse Recovery Current			82		A
E_{rec}	Reverse Recovery Energy			1.38		mJ
Q_r	Recovered Charge	$V_R=300\text{V}, I_F=150\text{A},$ $-di/dt=2400\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=125^{\circ}\text{C}$		11.4		μC
I_{RM}	Peak Reverse Recovery Current			106		A
E_{rec}	Reverse Recovery Energy			2.52		mJ
Q_r	Recovered Charge	$V_R=300\text{V}, I_F=150\text{A},$ $-di/dt=2400\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=150^{\circ}\text{C}$		13.3		μC
I_{RM}	Peak Reverse Recovery Current			112		A
E_{rec}	Reverse Recovery Energy			3.00		mJ

NTC Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
R_{25}	Rated Resistance			5.0		k Ω
$\Delta R/R$	Deviation of R_{100}	$T_C=100^{\circ}\text{C}, R_{100}=493.3\Omega$	-5		5	%
P_{25}	Power Dissipation				20.0	mW
$B_{25/50}$	B-value	$R_2=R_{25}\exp[B_{25/50}(1/T_2-1/(298.15\text{K}))]$		3375		K

Module Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Unit
L_{CE}	Stray Inductance		15		nH
$R_{CC'+EE'}$	Module Lead Resistance, Terminal to Chip		2.00		m Ω
$R_{\theta JC}$	Junction-to-Case (per T1-T4 IGBT)		0.248	0.273	K/W
	Junction-to-Case (per D1-D4 Diode)		0.437	0.481	
	Junction-to-Case (per D5,D6 Diode)		0.377	0.415	
$R_{\theta CS}$	Case-to-Sink (per T1-T4 IGBT)		0.281		K/W
	Case-to-Sink (per D1-D4 Diode)		0.495		
	Case-to-Sink (per D5,D6 Diode)		0.427		
$R_{\theta CS}$	Case-to-Sink		0.037		K/W
F	Mounting Force Per Clamp	40		80	K/W
G	Weight of Module		39		g

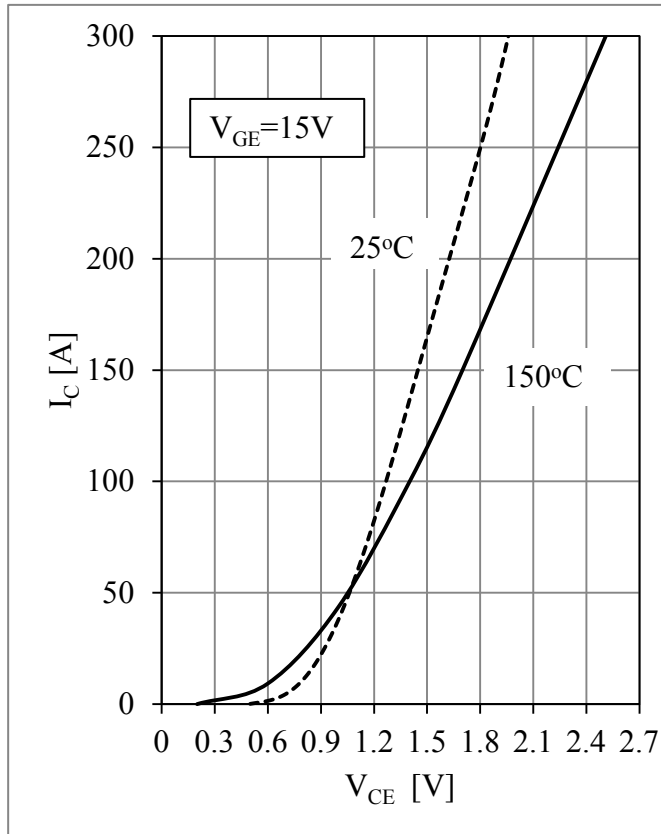


Fig 1. T1-T4 IGBT Output Characteristics

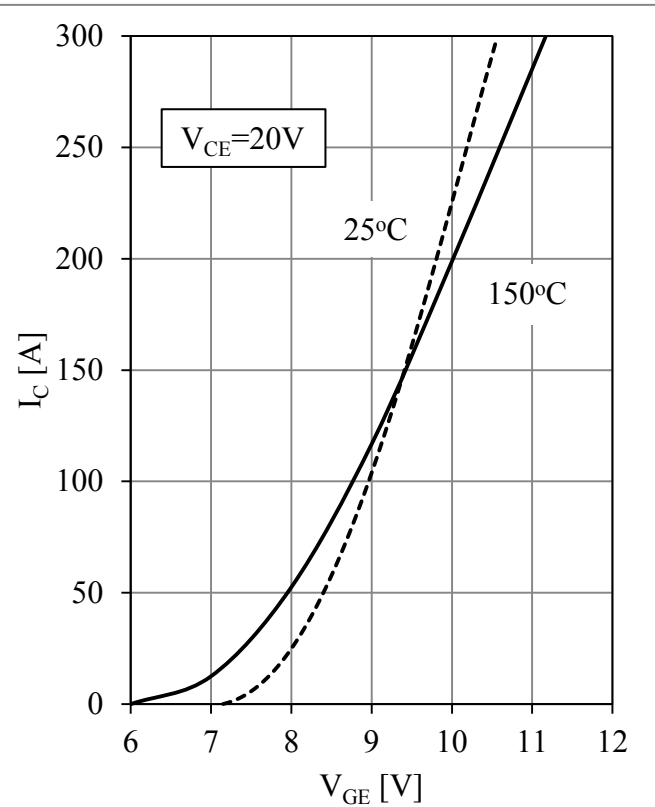
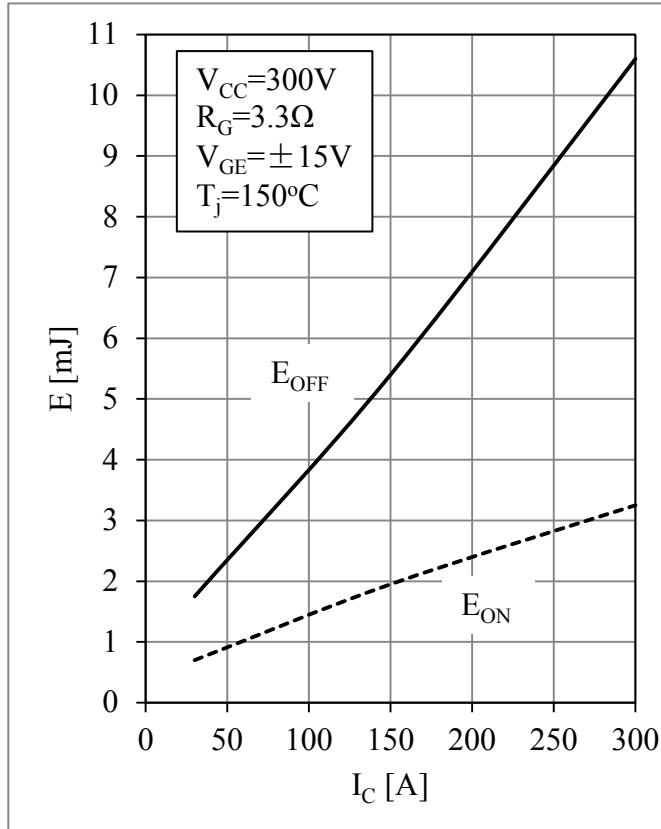
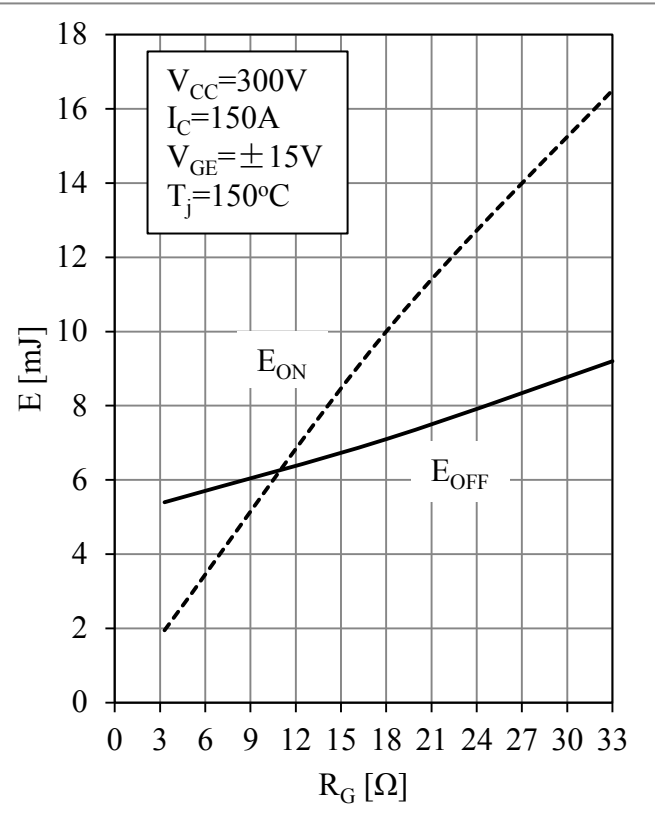


Fig 2. T1-T4 IGBT Transfer Characteristics

Fig 3. T1-T4 IGBT Switching Loss vs. I_C Fig 4. T1-T4 IGBT Switching Loss vs. R_G

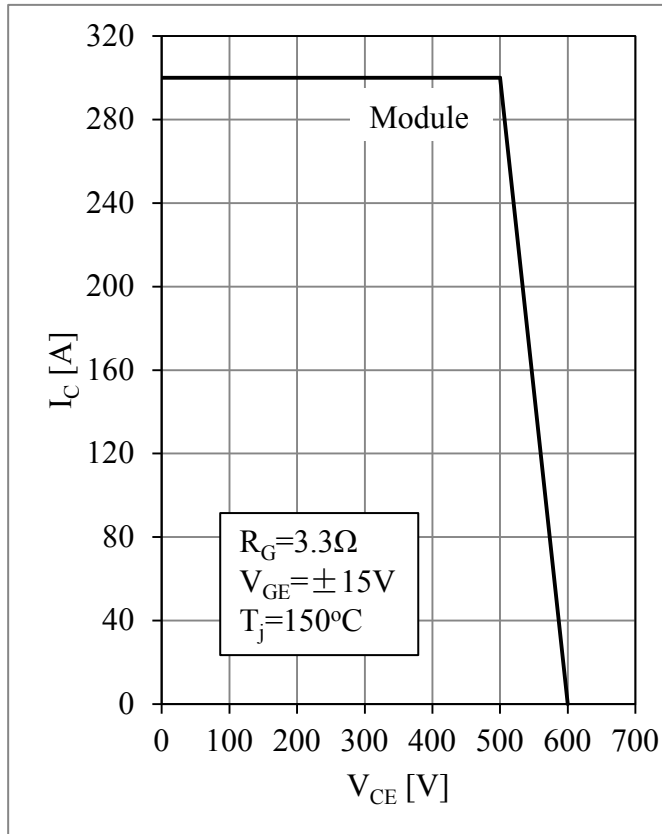


Fig 5. T1-T4 RBSOA

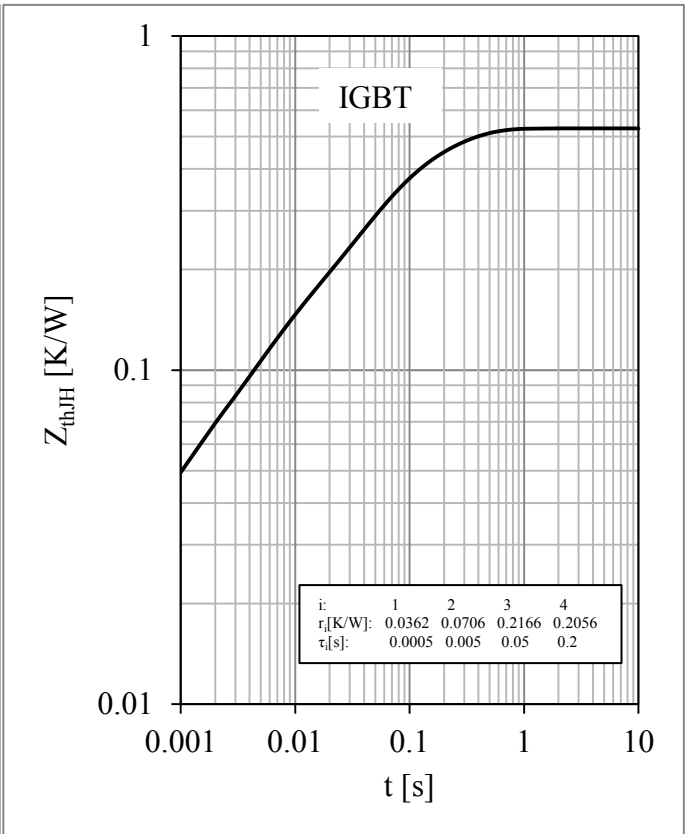


Fig 6. T1-T4 IGBT Transient Thermal Impedance

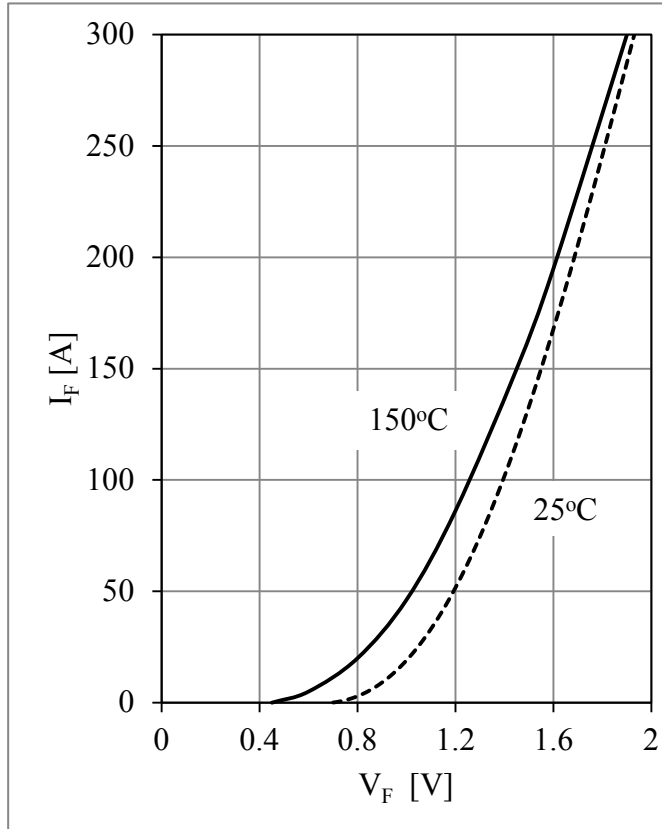
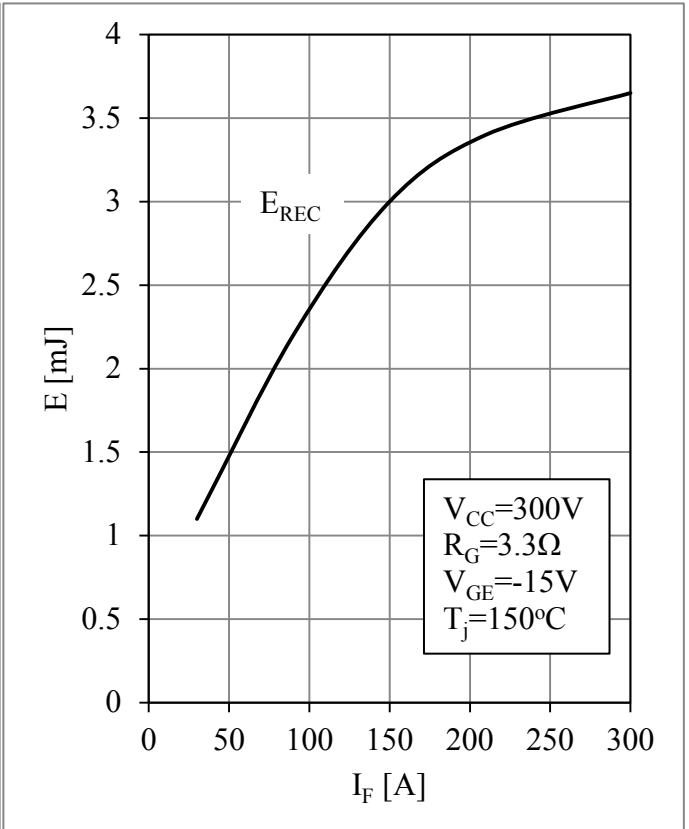
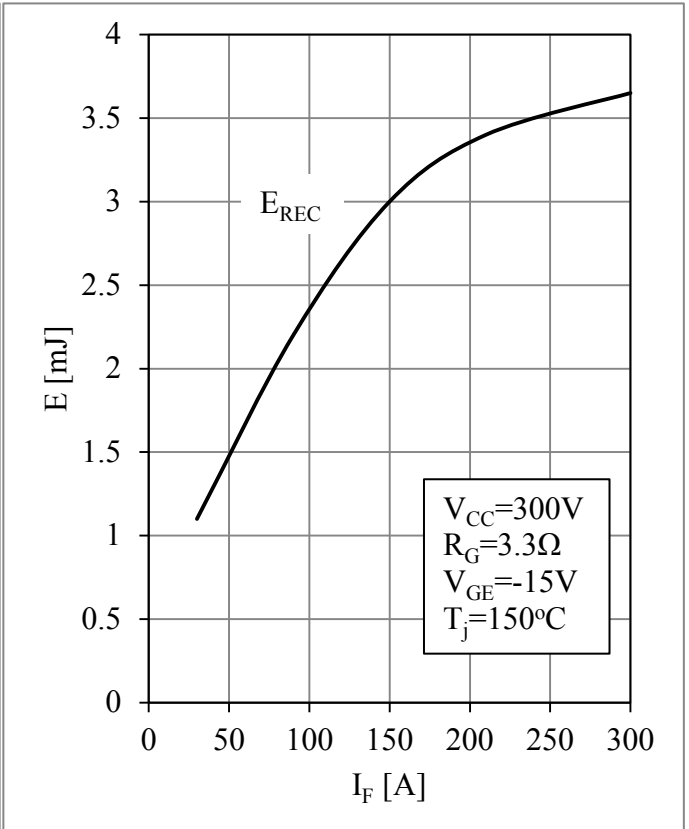
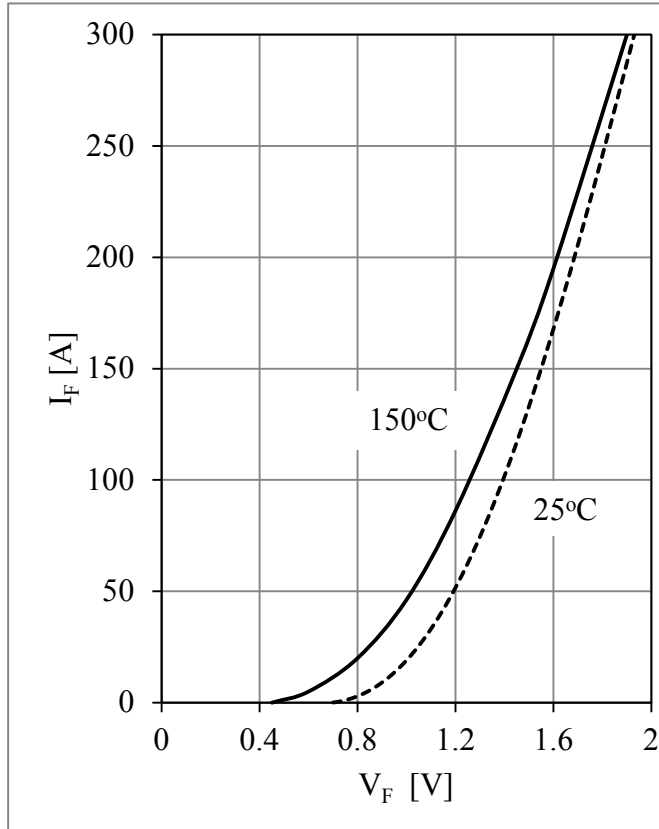
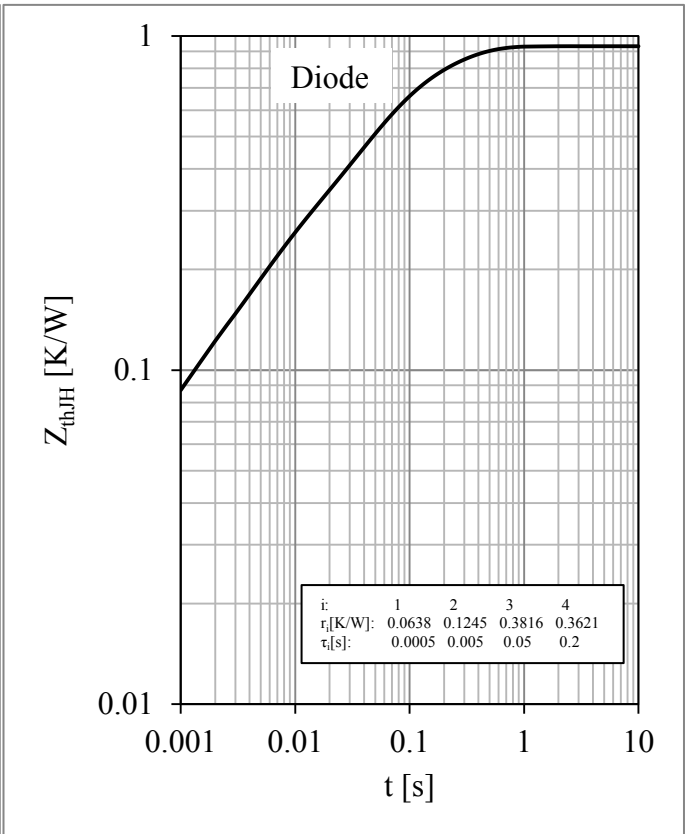
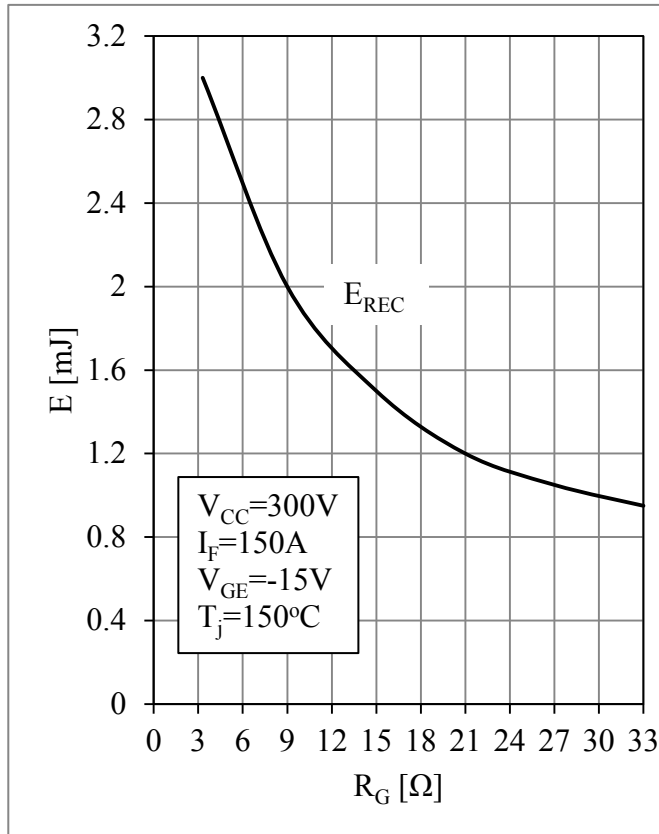
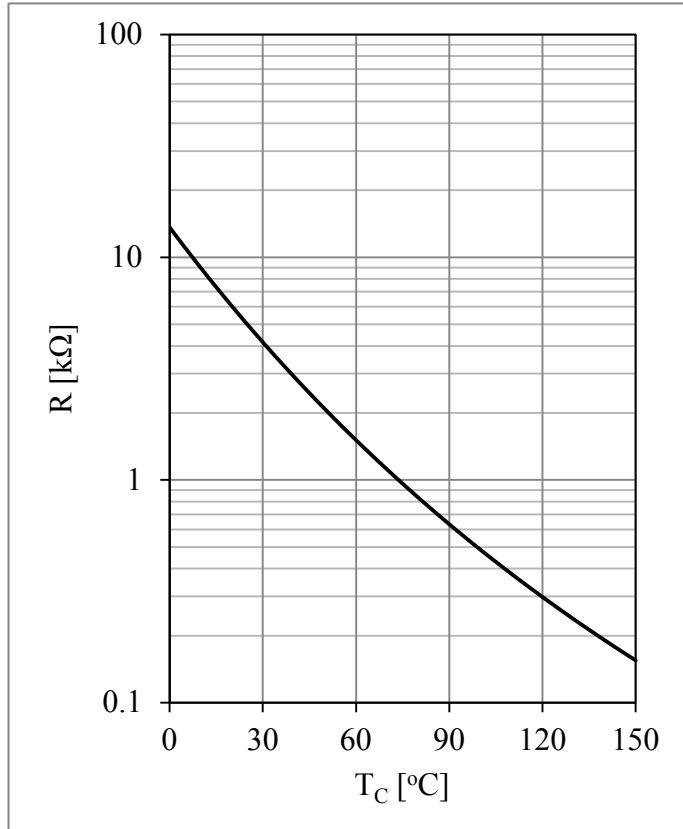
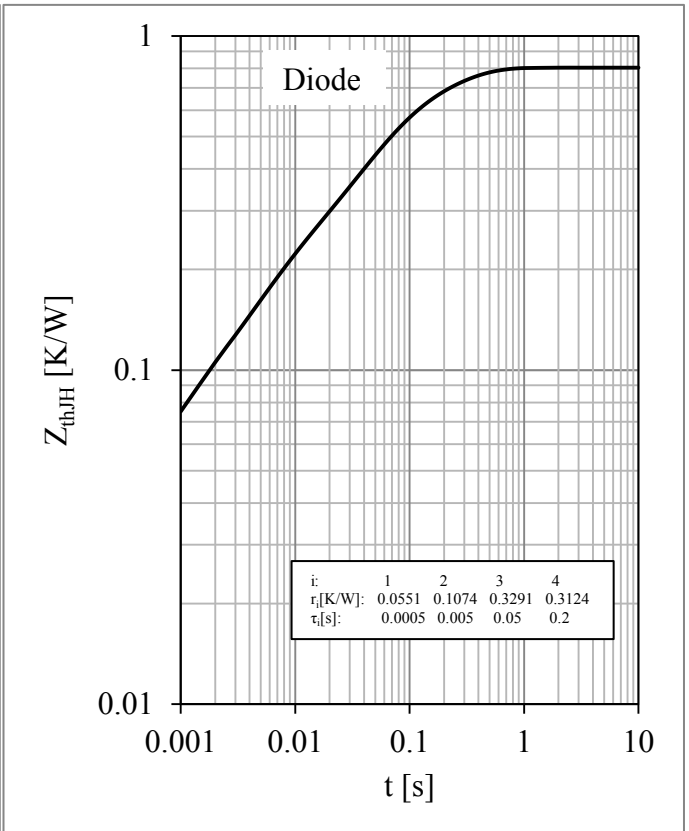
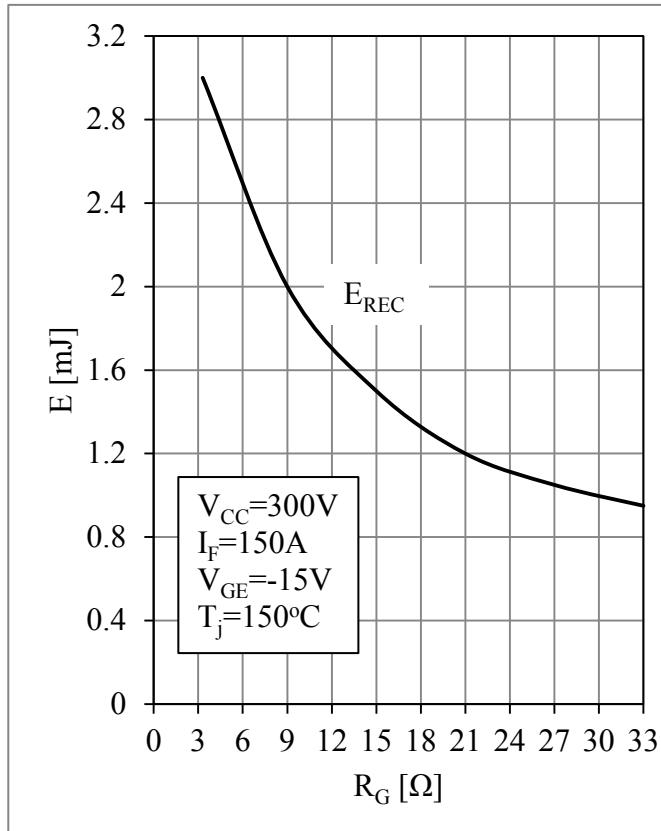


Fig 7. D1-D4 Diode Forward Characteristics

Fig 8. D1-D4 Diode Switching Loss vs. I_F





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